

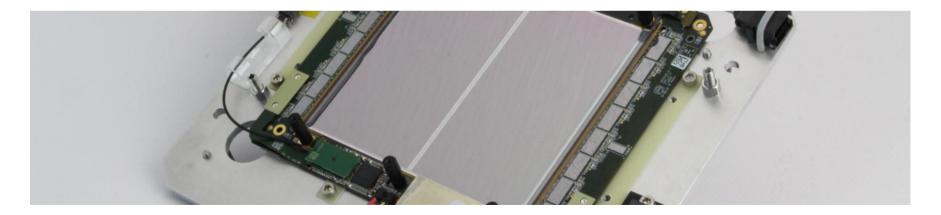




2S Module Production – Debriefing

ETP 2S Module Production Meeting – 27.03.2025

•Stefan Maier



www.kit.edu



Debriefing



Die Nachbesprechung ist ein Bericht über eine Mission oder ein Projekt oder die so erhaltenen Informationen. Es ist ein strukturierter Prozess nach einer Übung oder einem Ereignis, der die ergriffenen Maßnahmen überprüft.

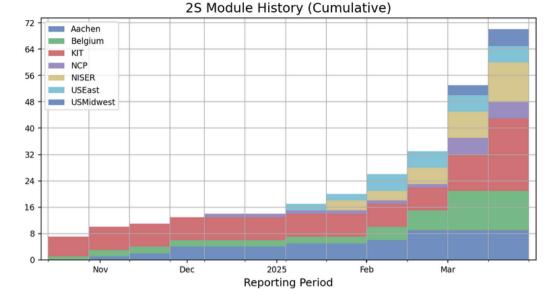
Source: Wikipedia (Englisch)



÷

15 Modules in 16 Days

Long story short: Success! We took the lead! ;)



								Kľ	T - 2S I	Module	DB Sta	atus (L	ast 60	Module	es)							
Carrier -																						
Attributes -																						
Production Date -																						
Module Test (final) -																						
4 Nodule Test (bonded) -																						
Module IV -																						
Pull Test -																						
Metrology -																						
VTRx+ -																						
SEH -																						
FEH-R -																						
FEH-L -																						
2 x 2S Sensor -																						
-	0003 -	- 10001	10002 -	10004 -	- 5000	- 1000	10006 -	- 1000	10008 -	0010 -	- 6000	- 1100	0012 -	0013 -	10014 -	0015 -	0016	- 100	- 6100	0021 -	020	0018 -
	KIT-10	KIT-10	KIT-10	KIT-10	KIT-10	KIT-10001	KIT-10	KIT-10	(IT-1(KIT-10	(IT-1(KIT-10	dT-10	KIT-10	KIT-10	KIT-10	KIT-10016	KIT-1001	KIT-1001	KIT-10	6_KIT-10020	KIT-10
	9	9	6	9	9	18_5_)	9	9	8_6_1	9	9	9	18_6_	9	9	8_6_1	6	9	9	9		9
	25_1(25_1(25_18	25_18	25_18	25_1(25_18	25_18	25_18	25_1(25_18	25_1(25_1(25_16	25_18	25_1(25_18.	25_18	25_18	25_18	25_18	25_18

s.maier@kit.edu



Shift Scheduling



- As already stated in the kick-off meeting the high granular scheduling of shifts and task is not feasible for a full scale production scenario
- We will change from 8 time slots to 4 time slots
 - 2 in the morning 2 in the afternoon
 - One "major" gluing task per 2 shifts
- Try to keep HiWis busy
 - Dicing test
 - VI hybrids
 - Skeleton assembly and test
 - VI Bridges
 - Assemble carriers
 - Register parts on arrival \rightarrow Logistics room ;)
- We remove starting and end times as we will drop constraints in the pipeline



Pipeline in general

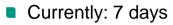
- Currently: 7 days
 - Kapton gluing
 - O.I. & Wire-bonding & encapsulation
 - HV / IV test & Bare module assembly
 - O.I. & Metrology & Hybrid gluing
 - O.I. & Wire-bonding & quick test & encapsulation
 - Encapsulation
 - Full test
 - 7 days



- In future: 13 days
 - Kapton gluing
 - O.I. & Wire-bonding & Encapsulation
 - HV / IV test
 - Bare module assembly
 - O.I. Bare Modules
 - Metrology
 - Hybrid gluing
 - O.I. Hybrid gluing
 - Wire-bonding
 - Quick test
 - Encapsulation
 - Encapsulation
 - Full test



Pipeline in general



- Kapton gluing
- O.I. & Wire-bonding & encapsulation
- HV / IV test & Bare module assembly
- O.I. & Metrology & Hybrid gluing
- O.I. & Wire-bonding & quick test & encapsulation
- Encapsulation
- Full test
- 7 days



- In future: 13 days
 - Kapton gluing
 - O.I. & Wire-bonding & Encapsulation
 - HV / IV test
 - Bare module assembly
 - O.I. Bare Modules
 - Metrology
- Time constraint in our pipeline
- Hybrid gluing
- O.I. Hybrid gluing
- Wire-bonding
- Quick test
- Encapsulation
- Encapsulation
- Full test



6



Pipeline in general

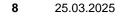


- In future: 13 days
 - Kapton gluing
 - O.I. & Wire-bonding & Encapsulation
 - HV / IV test
 - Bare module assembly
 - O.I. Bare Modules
 - Metrology
 - Hybrid gluing
 - O.I. Hybrid gluing
 - Wire-bonding
 - Quick test
 - Encapsulation
 - Encapsulation
 - Full test

Constraint

- Limited by #of jigs
- Constrains us to do O.I. immediately followed by HV tail bonding
- Kapton gluing in the afternoon not feasible as the glue will not harden enough
- Module bonding schedule must account for this:
 - Start only one module in the morning
 - Wire-bond tails
 - Bond remaining modules





Stefan Maier



Front-End

- Basic functionalities given by the software
 - Login problems solved
- Improvements mandatory
 - Better overview pages
 - Display of part history (comments)
 - Edit tasks already done
- Please use the comment field!
 - Unify way of giving comments?

Lets hope our HiWis are good with JavaScript!



Skeleton Assembly and Test



Hybrid VI:

- Leander identified 3 FEHs with scratches on the antenna and GND bond pads
- We concluded that we identify such hybrids with a red sticker to make clear that wire-bonding might be problematic
 - Could also be done via the front-end but given the severity this is more straight forward and indicative

Skeleton assembly is a time consuming step

- We will try to stick and let it be done by HiWis, but this might not fully work out
- Skeleton test can be run while another one is assembled





AI-CF Bridges



- With new no-go pins all "newer" bridges passed hole QC test
- Thickness gauges machined by brown questionable
 - Results in 10% dropout rate, contacted conveners
 - We were told to measure bridges manually to crosscheck their gauges...

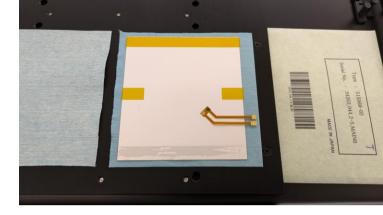
05.03.2025	Lorena	1.8 Stump	Tray 4	72				too thin	17	5486_22			
								too thin	18	5486_22			
								too thin	24	5486_18			
								too thin	29	5486_18			
								too thin	51	5488_05			
								too thin	68	5488_06			
5.03.2025	Lorena	1.8 Stump	Tray 3	72				too thin	1	5443_04			
								too thin	5	5443_05			
								too thin	6	5443_05			
								too thin	10	5443_05			
								too thin	12	5443_05			
								too thin	44	5486_19			
								too thin	58	5486_24			
								too thin	70	5486_27			
11.03.2025	Lorena	1.8 Main	Tray 26	16	missing	2	5514_18_2						
11.03.2025	Lorena	1.8 Main	Tray 27	16							slot too large	2	5486_4_1
					broken	13	5409_10_2						
11.03.2025	Lorena	1.8 Main	Tray 28	16	Stufe	7	5409 18 2						

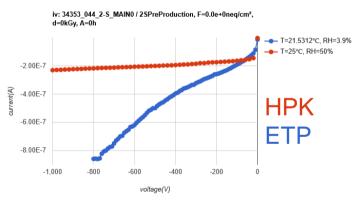


Kapton Gluing

- Incident: Pickup tool stuck to sensor
 - Repairable
 - Increased IV curve. Not severe
 - Amount of glue in the pattern was reduced by 10%
- We try and stick to do the gluing in the morning shift
 - Keep 24h of curing as we need to wire-bond this in the morning
- Recheck of gluing in the afternoon
- Sensor showed some scratches during/after bare module assembly
 - Assumption: They come from the repair
- Buy dedicated dropper/pipette to apply isopropanol









Stefan Maier

Sensor handling / Sensor Dicing



Now: Sensor processes is started after dicing test



HV Tail Bonding and Encapsulation



Bonding went flawless

- Pattern recognition even better with new tails
- Ease front-end usage: We skip the location scan, implemented



HV / IV Test

- Sensor tablets are now tagged:
 - One caveat: First person in the morning must change tags from curing to untested. Error Prone How does one know he /she is the first one? Ideas?
- Current recipe for measurement: 20 mins if everything goes well
 - Place sensor, attach HV tail
 - Place ion blower for 3-5 minutes
 - Place bias needle
 - Wait for 5% RH
 - Measure
- Problem sensors do charge up / are charged up after the HV test
 - We had >500V on the jig after the measurement!
 - Check relay setting and investigate
 - Possible damage on sensors? (See later damaged channels)







Stefan Maier

Microscopes on Gluing Stations



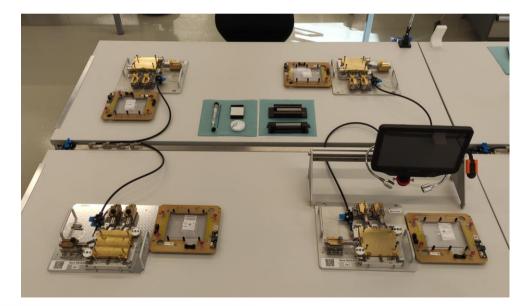
Looking forward for their upgrade
Should be done before we re-start
Experience with batteries?



Bare Module Assembly / Metrology



- Space sufficient for 2 jigs/table?
- Different jigs yield slightly different alignment results
 - Eager to see trends
 - Recheck alignment pins
- Jig #3 base plate uneven?

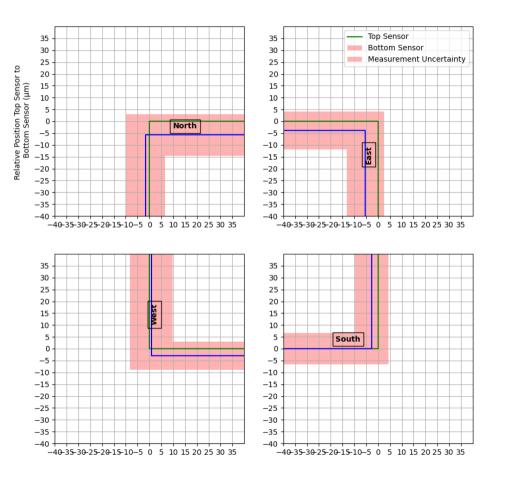


Stefan Maier

s.maier@kit.edu



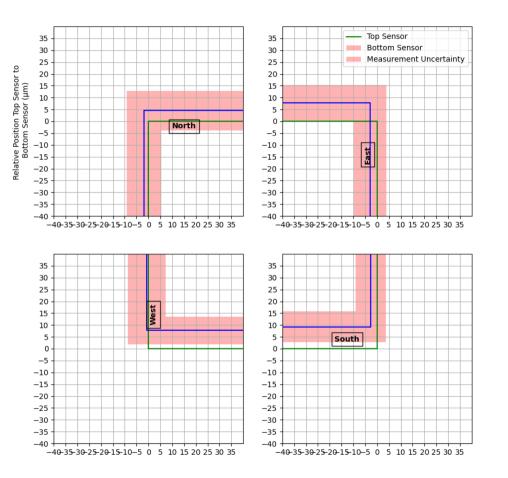
Modul 12 Jig 1







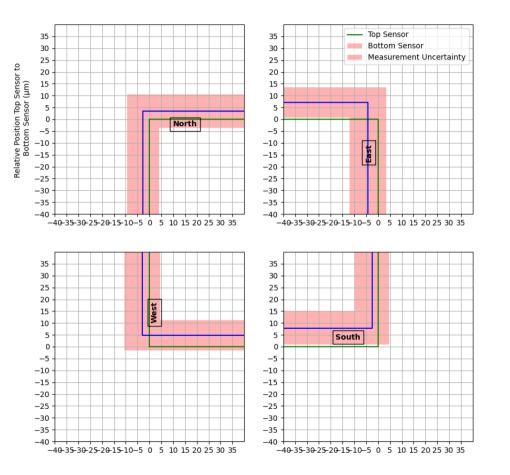
Modul 15 Jig 1







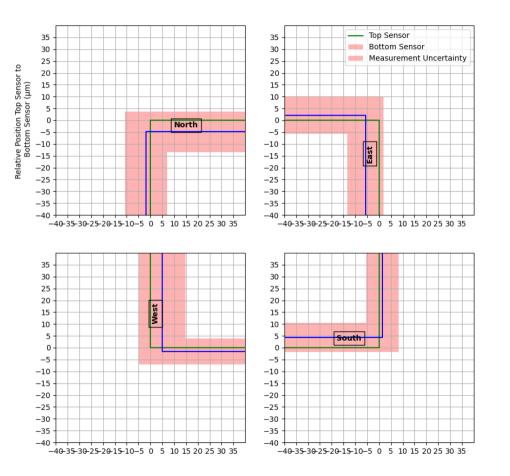
Modul 20 Jig 1







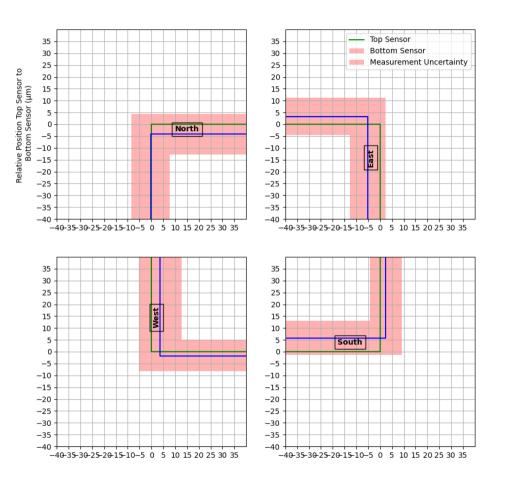
Modul 13 Jig 2





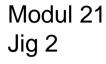


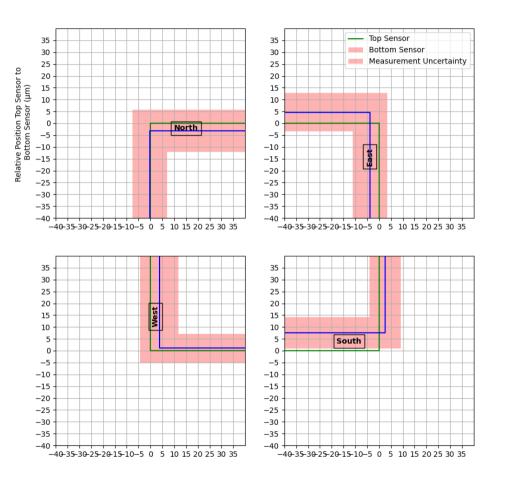








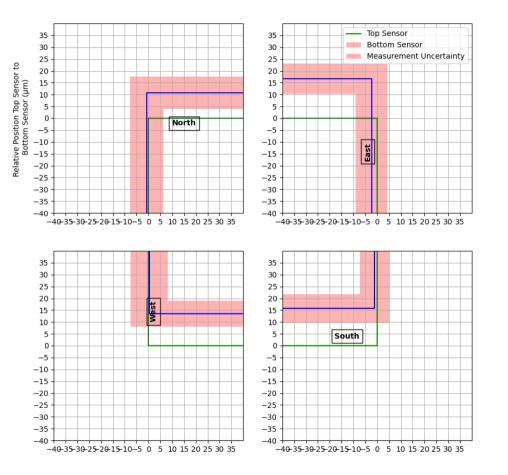








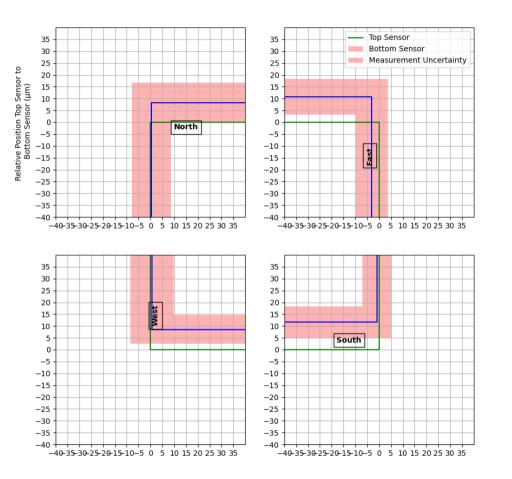
Modul 16 Jig 3







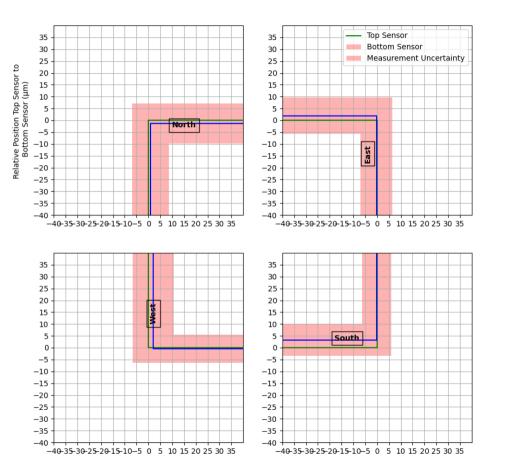
Modul 19 Jig 3







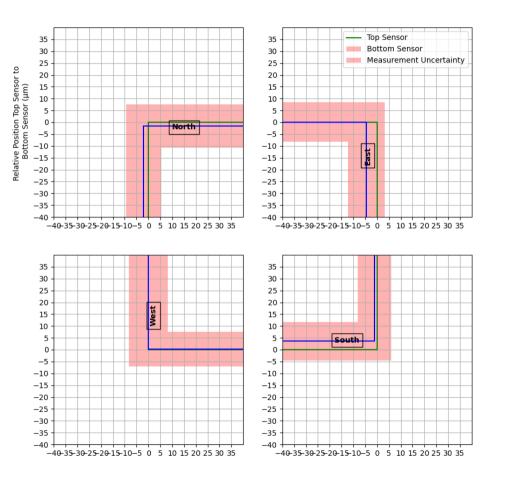
Modul 17 Jig 4







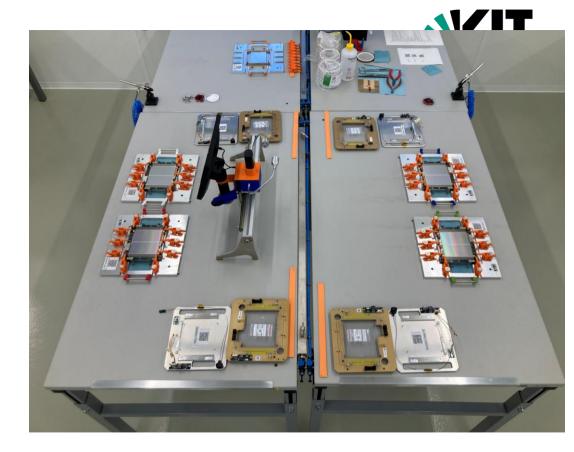
Modul 18 Jig 4





Hybrid Assembly

- Sufficient space for 2 jigs/table?
- Further comments?

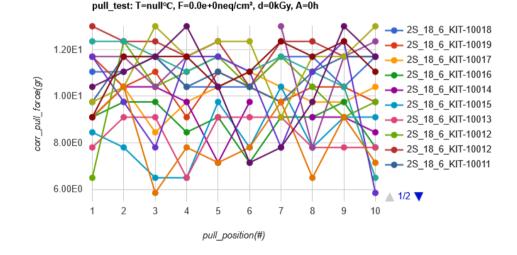




Stefan Maier

Stefan Maier

s.maier@kit.edu



In general even smoother than in October

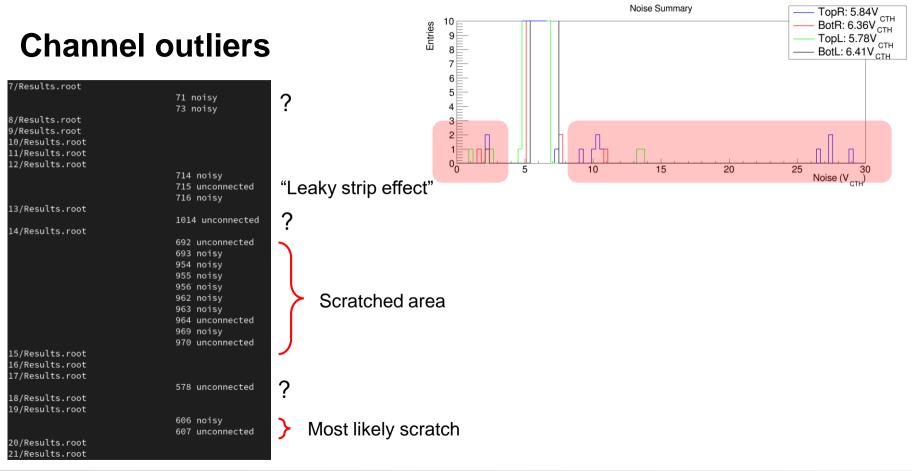
- 4 modules and 20 pull test wire-bonds: 4 hours and 30 minutes
- Where is the bottleneck?
 - \rightarrow PARTS
- All pull test values between 6 and 13 g

Wire-bonding

Add dedicated microscope to make these pull tests and to inspect modules (?)









30 25.03.2025

Stefan Maier



- Clash of MT / MPO connector (Zip tie) with module adapter
 - Already modified, might need to reprint plastic piece
- 5cc and 30cc usage exercised
 - Both run smooth

Encapsulation

- Might need to adapt the 30cc program slightly
 - Did not 100% hit the wire-bond feet on last modules, to be investigated
 - Change dispensing height
- 6 modules tested with WBE height tool. All passed (<1mm above bottom sensor)</p>
 - 9 more (incl 30cc modules) to do…

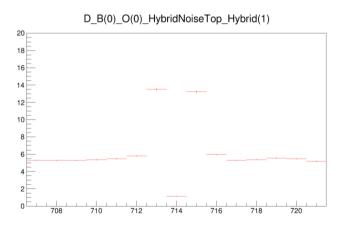


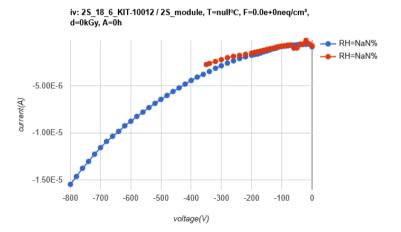
Stefan Maier

modo (1 Modulo i

Module Test

- New failure mode (1 Module in October and one this time)
- Single channel increases global leakage current significantly
- Until we do not understand the cause and the impact on operation we must identify these channels and pull the corresponding channel
 - We will start testing how this is triggered and its impact

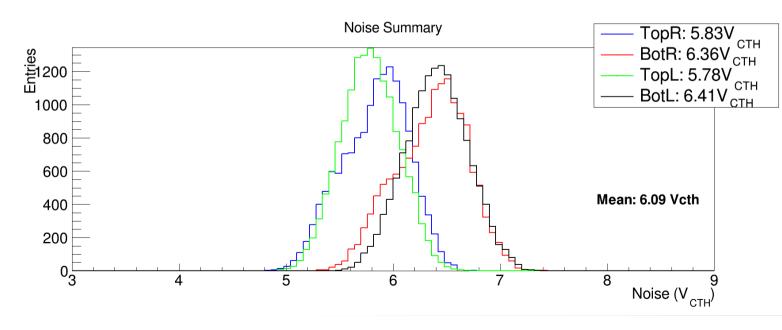








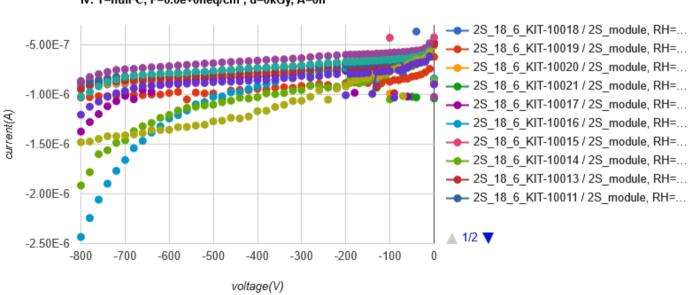
Module Test (2) - Noise







Module Test (3) - IV







Organization



- Vacation / sickness leave etc: How to run the assembly line?
- Need to come up with some knowledge transfer
 - At the moment a lot of things happen "in the background" using custom scripts and manual work





Outlook

- Soon, we will get more FEHs
 - They will have blocked alignment holes. Assembly without pins
- New HV Tails are currently prepared at CERN.
 - Update expected tomorrow in the electronics meeting
 - IF they are good we can expect them mid of April
- We expect ~120 or more carriers "soon"
 - Assembly time should not to be underestimated
- New type of SEH will be build "soon", we do not expect that we need to build too much incomplete modules anymore
- Soon: New modules must be finalized with another SEH
 - Hybrid gluing
 - Light shield attachment (encapsulant)
 - Single module full test
 - Burn in
- Once we ramp again we will again start only doing one module per day, increasing towards 4 modules per day, depending on how much material we get. We will try to enter in a continuous production.



structure	Count	Assembled	Available
<u>2S_carrier</u>	25	12	<u>13</u>
2S Sensor	3522	84	<u>3438</u>
2 <u>S_Skeleton</u>	38	31	Z
<u>Al_cf_bridge_long_18</u>	270	66	<u>181</u>
<u>Al_cf_bridge_long_40</u>	198	2	<u>181</u>
Al_cf_bridge_short_18	339	58	<u>251</u>
<u>Al_cf_bridge_short_40</u>	178	2	<u>176</u>
<u>fehybrid_left</u>	64	40	<u>24</u>
<u>fehybrid_right</u>	69	42	27
gnd_balancer	119	24	<u>95</u>
hvtail_bottom	46	46	<u>0</u>
<u>hvtail_top</u>	45	45	<u>0</u>
kapton_long	556	150	<u>401</u>
kapton_short	540	133	<u>407</u>
service_hybrid	101	40	<u>61</u>
VTRxPlus	118	25	<u>93</u>

Vacation



Dierlamm																																	
April	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19 <mark>2</mark>	0 21	22	23	24	25	26	27	28	29	30				
Barvich				1										1	1	1	1					L 1	. 1	1									
I Siemens																																	
2 Krämer																																	
8 Rehm											1								Osterr	n													
4 Berger														1	1	1	1																
5 Simonis																																	
5 Maier																											1	1	1				
7 Dierlamm																																	
8 Mai			1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17 1	8 19	20	21	22	23	24	25	26	27	28	29	30	31	
Barvich				1										1	1	1	1	1													1		
) Siemens																																	
l Krämer				1																											1		
2 Rehm																															1		
Berger			1.Mai	1																											1		
1 Simonis																																	
, onnorma																																	
5 Maier				1			1	1	1	1																							
				1			1	1	1	1																							

